



K8LPF2

chip dimensions: 210 x 110 mils
substrate: 5 mil thick Alumina
metalization: WTi with 200u" Au for wire bonding
resistors: TaN, 50 Ohms/square
vias: 3 mil diameter, plated-thru
layers:

chip outline = cyan
top metal = black
backside metal = blue
vias = green
resistors = red

NATIONAL RADIO ASTRONOMY OBSERVATORY

1180 Boxwood Estate Rd, Charlottesville, VA, 22903

NAME: k8lpf2

FILE: k8lpf2.dwg

DATE: 3/20/2008

BY: Matthew A. Morgan

E-MAIL: matt.morgan@nrao.edu